

Circuit connecting material, film-like circuit connecting material using the same, circuit member connecting structure, and method of producing the same

Publication number: CN1723590 (A)

Publication date: 2006-01-18

Inventor(s): KAZUYOSHI ARIFUKU MOTOHIRO WAT [JP]

Applicant(s): HITACHI CHEMICAL CO LTD [JP]

Classification:





- international: *H01R11/01; C09J9/02; C09J163/00; H01B1/00; H01B1/22; H01L21/60; H05K1/14; H05K3/32; H05K3/36; H05K3/34; H01R11/01; C09J9/00; C09J163/00; H01B1/00; H01B1/22; H01L21/02; H05K1/14; H05K3/32; H05K3/36; H05K3/34*

- European: C09J9/02; C09J163/00; H01B1/22; H01L21/60D; H05K3/32B2

Application number: CN20048001836 20040624

Priority number(s): JP20030181593 20030625

Also published as:

 CN100380741 (C)
 EP1628363 (A1)
 EP1628363 (A4)
 US2006100314 (A1)
 KR20050074641 (A)

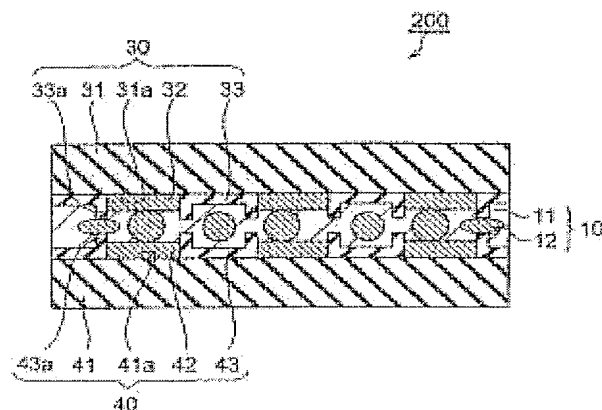
more >>

Abstract not available for CN 1723590 (A)

Abstract of corresponding document: **EP 1628363 (A1)**

The present invention is a circuit connecting material used for the mutual connection of a circuit member in which electrodes and insulating layers are formed adjacent to each other on the surface of a board, and a circuit member in which electrodes and insulating layers are formed adjacent to each other on the surface of a board, with the edge parts and of the insulating layers being formed with a greater thickness than the electrodes on the basis of the main surfaces, wherein this circuit connecting material contains a bonding agent composition and conductive particles that have a mean particle size of 1 [μ m] or greater but less than 10 [μ m] and a hardness of 1.961 to 6.865 GPa,; and this circuit connecting material exhibits a storage elastic modulus of 0.5 to 3 GPa at 40 DEG C and a mean coefficient of thermal expansion of 30 to 200 ppm/DEG C at from 25 DEG C to 100 DEG C when subjected to the curing treatment.

Fig.1



Data supplied from the **esp@cenet** database — Worldwide